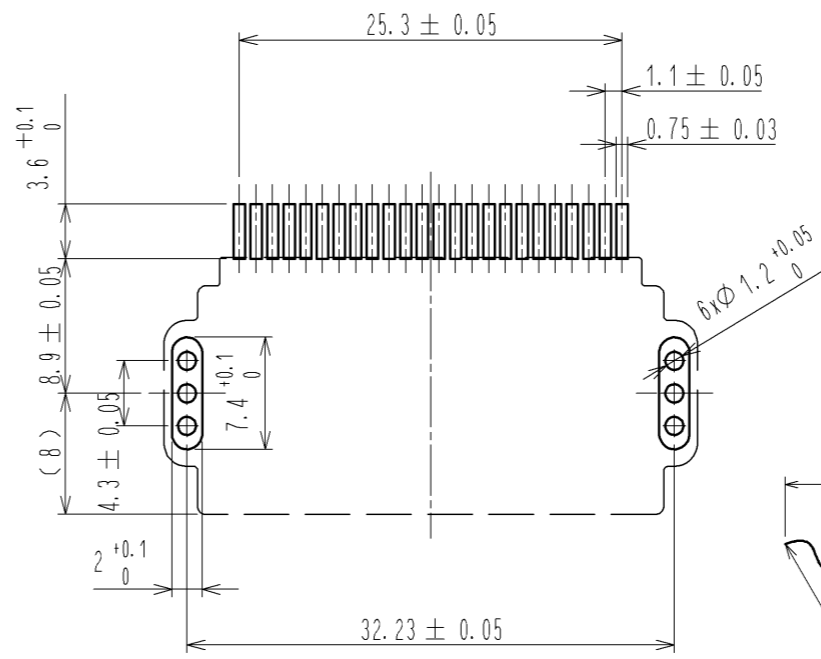
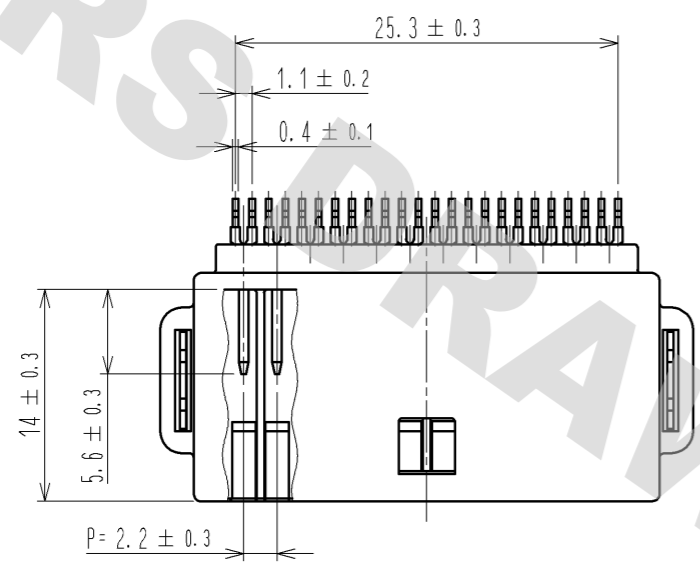
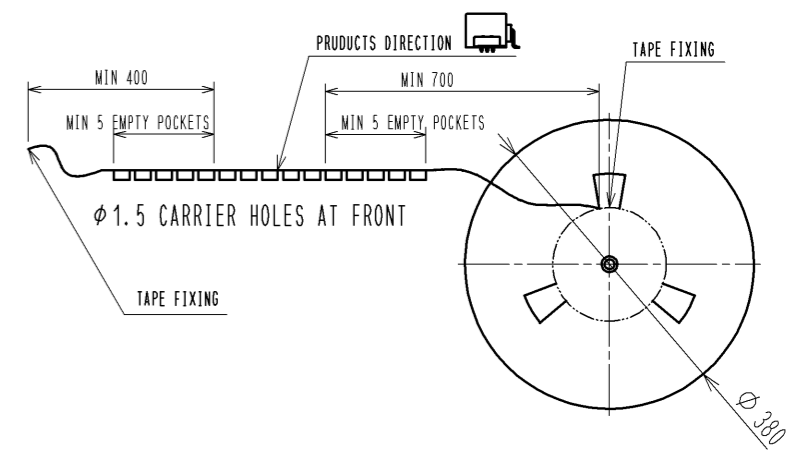


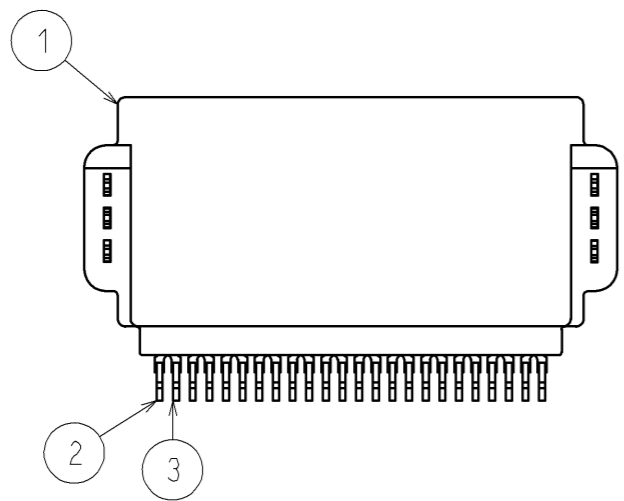
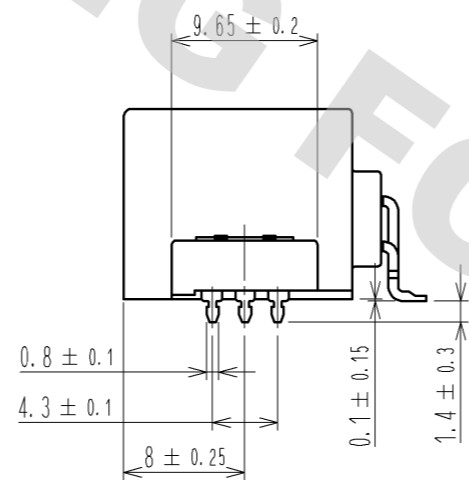
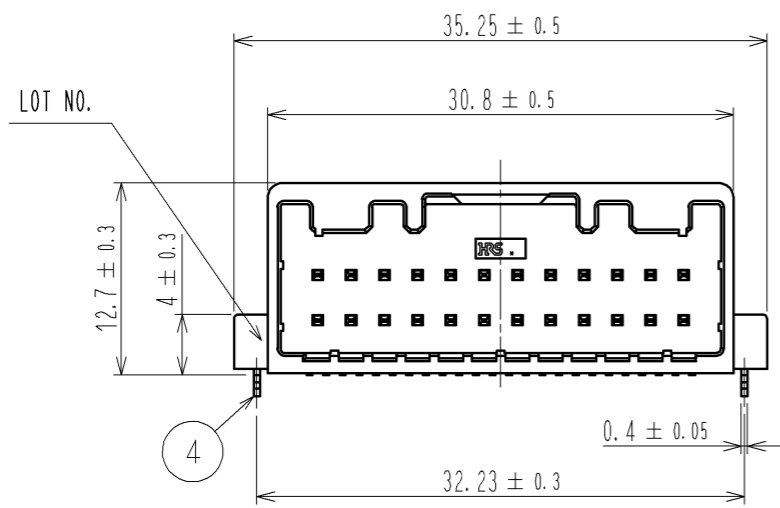
ELV, RoHS COMPLIANT



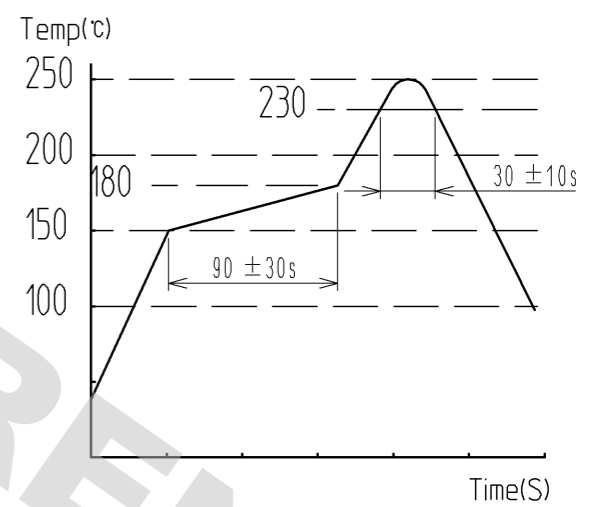
RECOMMENDED PC BOARD PATTERN



EMBOSS SPECULATION



- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.)  
 USED REFLOW SYSTEM : IR IN THE AIR OR NITROGEN  
 NO. OF CYCLES : 2 MAX  
 PEAK : 250°C  
 OVER 230°C : 20~40s  
 PREHEAT : 150~180°C  
 60~120s  
 2. TEMPERATURE FOR SOLDERING IRON : 280~300°C WITHIN 2s  
 3. CO-PLANARITY SHALL BE 0.1 MAX.  
 4. PC BOARD THICKNESS=1.6.  
 5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64	4	BRASS	TIN PLATED	T=0.4
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	T=0.64
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
UNITS	mm	SCALE	2 : 1	COUNT	1	DESCRIPTION OF REVISIONS	DESIGNED
						DIS-T-003532	TY. SAKASHITA
							CHECKED
							TY. TAKAHASHI
							DATE
							13. 10. 01
APPROVED : KS. SATOH		07. 04. 25		DRAWING NO.		EDC3-166409-00	
CHECED : AR. SHIRAI		07. 04. 19		PART NO.		GT25-24DP-2. 2H	
DESIGNED : TY. SAKASHITA		07. 04. 19		CODE NO.		CL775-0007-0-00	
DRAWN : TY. SAKASHITA		07. 04. 19					

DRAWING FOR REFERENCE: This is subject to change without notice 12/05/2013